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Nota di contenuto	Lead-free Electronics; Contents; Preface; Editors; Contributors; Acknowledgments; Chapter 1 Lead-free Electronics: Overview; 1.1 What Is Lead-free?; 1.2 Why Lead-free?; 1.2.1 Legislation; 1.2.2 Market differentiation; 1.2.3 Environmental stewardship; 1.3 Who Are the First Consumers for Lead-free Products?; 1.3.1 Affluent societies; 1.3.2 Social/cultural motivation; 1.3.3 Consumer response to lead-free electronics; 1.4 Are There Any Technical Barriers to Lead-free Electronics?; 1.4.1 Technical issues; 1.4.2 Reliability concerns; 1.5 How Will We Migrate to Lead-free Electronics? 1.5.1 Potential mismatches: obsolescence and compatibility 1.5.2 Supply chain issues; 1.6 When Will Lead-free Products Be Widely Available?; 1.6.1 Recycling and material recovery systems; 1.7 summary; 1.8 References; Chapter 2 Lead-free Legislations, Exemptions, and Compliance; 2.1 Overview of the Lead-free Legislation; 2.1.1 WEEE Directive; 2.1.2 RoHS Directive; 2.1.3 Electronic

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2.2.2 Lead in high melting temperature type solders2.2.3 Lead in solders for servers, storage and storage array systems; 2.2.4 Lead in solders for network infrastructure equipment; 2.2.5 Lead in electronic ceramic parts; 2.3 Impact of Exemptions; 2.3.1 Military electronics; 2.3.2 Automotive electronics; 2.3.3 Avionics; 2.3.4 Oil and gas well electronics; 2.3.5 Medical electronics; 2.3.6 Industrial. network infrastructure, server and storage electronics; 2.3.7 Risks due to exemptions; 2.4 Compliance with the Legislation; 2.5 Recommendations and Conclusions; 2.6 References  
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## Sommario/riassunto

Lead-free Electronics provides guidance on the design and use of lead-free electronics as well as technical and legislative perspectives. All the complex challenges confronting the elec-tronics industry are skillfully addressed:  
\* Complying with state legislation  
\* Implementing the transition to lead-free electronics, including anticipating associated costs and potential supply chain issues  
\* Understanding intellectual property issues in lead-free alloys and their applications, including licensing and infringement  
\* Implementing cost effective manufacturing and testing  
\* Reducin

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